



100% Material Declaration Data Sheet PQG100

PK121 (v1.3.1) October 19, 2006

Material Declaration Data Sheet

Average Weight: 1.6 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.03472	2.17%
	Silicon	7440-21-3	100.00		0.03472	
Die Attach Material					0.00544	0.34%
	Silver	7440-22-4	78.00		0.0042432	
	Epoxy (EP)	Trade Secret	22.00		0.0011968	
Mold Compound					1.24624	77.89%
	Epoxy Resin (EP)	Trade Secret	9.00		0.1121616	
	Phenolic Resin	Trade Secret	7.00		0.0872368	
	Carbon Black	1333-86-4	0.50		0.0062312	
	Silica	60676-86-0	82.50		1.028148	
	Bismuth	7440-69-9	Max 1.00		0.0124624	
Leadframe					0.2856	17.85%
	Copper	7440-50-8	98.85		0.2823156	
	Chromium	7440-47-3	0.30		0.0008568	
	Tin	7440-31-5	0.25		0.000714	
	Zinc	7440-66-6	0.60		0.0017136	
Leadframe Plating					0.0024	0.15%
	Silver	7440-22-4	100.00		0.0024	
Bond Wire					0.00368	0.23%
	Gold	7440-57-5	100.00		0.00368	
Ext. Plating					0.02192	1.37 %
	Tin	7440-31-5	100.00		0.02192	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
6/08/06	1.1	100% Material Declaration.
8/16/06	1.2	Corrected all weight values.
9/28/06	1.3	Updated component descriptions.
10/19/06	1.3.1	Editorial change; corrected typo in Substance Description.